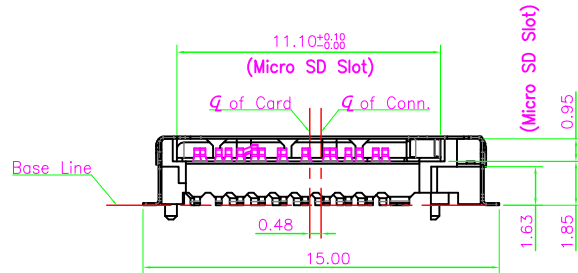
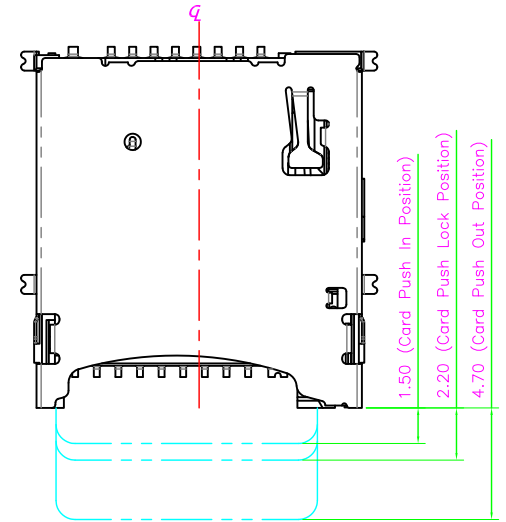
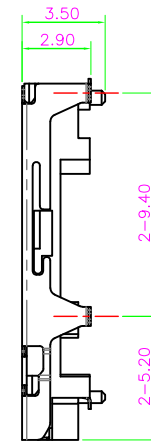
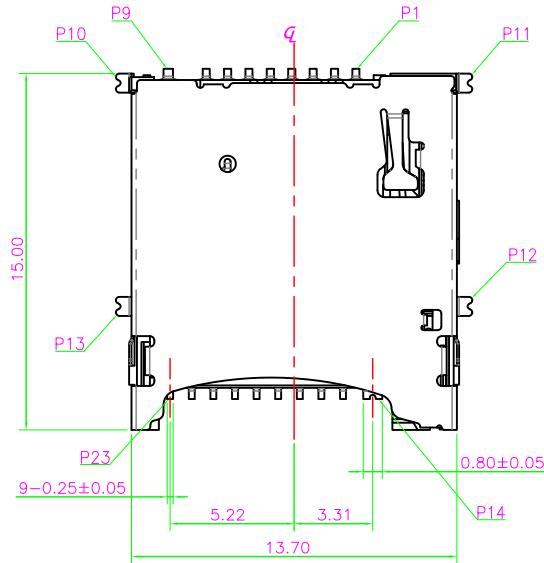
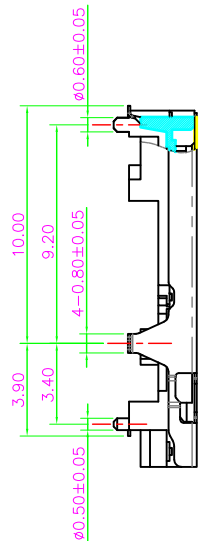
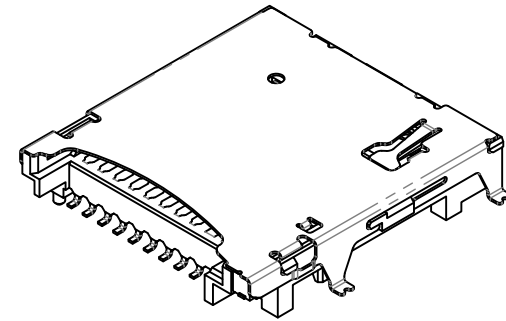
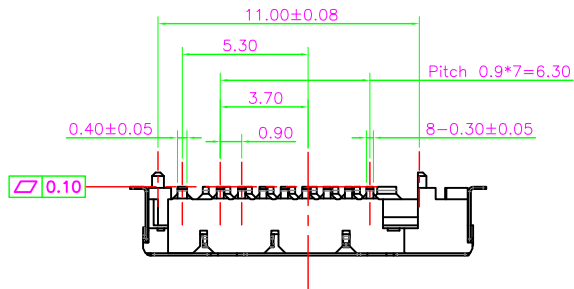


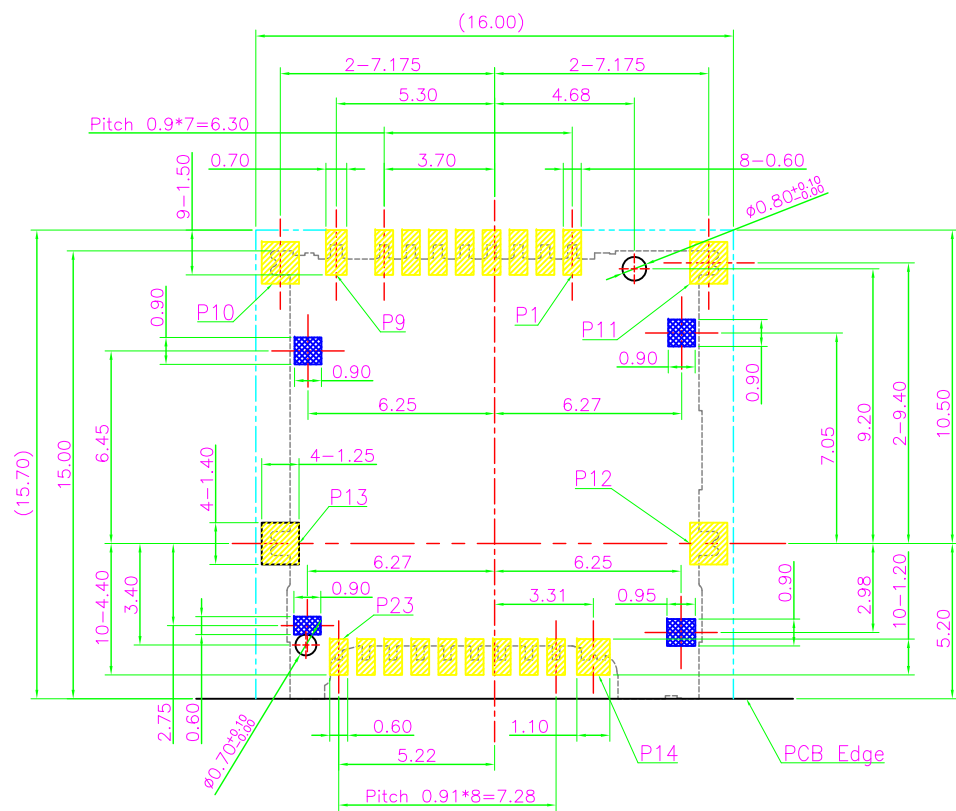
更改 REV	变更内容 MODIFICATION
A	ECXXXXX



GENERAL TOLERANCE		KINGCONN 皇海科技股份有限公司	
X.± 0.50	X.° ± 5°	名 称(TITLE) MICRO SD 4.0 PUSH H:1.63MM SMD	
.X± 0.30	.X° ± 2°		
.XX± 0.20	.XX° ± 1°		
单 位(UNIT) mm	料 号(PART NO.) 7MSD4-F0-0003	图 号(DWG NO.) 7MSD4-F0-0003	比例 SCALE 1:1
审 核(APPROVAL)	核 对(CHECKED)	製 图(DRAWN)	张 数 SHEET 1/2
			更 改 REV A



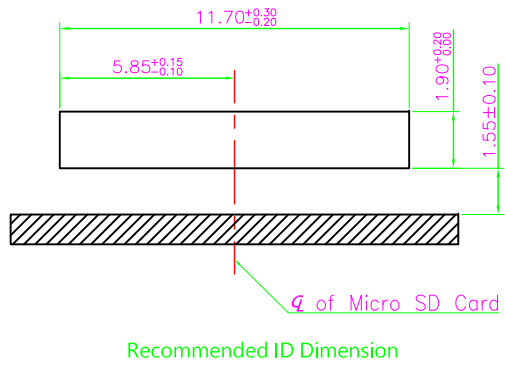
更改 REV	版本 MODIFICATION
A	ECXXXXX



- Pad Area
- No Component Area
- Red Gluing Area
- Product Area

Recommended PCB Layout
Top View (Tolerance ±0.05)

	Card Detect Switch
Card Uninsertion	Open
Card Half Insertion	Open
Card Insertion	Close
Open	Close



Pin No.	Pin Assignment
P1	Micro SD DAT2
P2	Micro SD CD/DAT3
P3	Micro SD CMD
P4	Micro SD VDD1
P5	Micro SD CLK
P6	Micro SD VSS
P7	Micro SD DAT0/RCLK+
P8	Micro SD DAT1/RCLK-
P9	Micro SD CD
P10	GND
P11	GND
P12	GND
P13	GND
P14	GND
P15	Micro SD VDD2
P16	Micro SD SWIO
P17	Micro SD VSS
P18	Micro SD D0+
P19	Micro SD D0-
P20	Micro SD VSS
P21	Micro SD D1-
P22	Micro SD D1+
P23	Micro SD VSS

- Note :
- Material :
 - 1-1. Plastic : LCP, Black, UL94V-0
 - 1-2. Contact : C5210
 - 1-3. Shell : SUS304
 - Plating :
 - 2-1. Contact :
 - Contact Area: Au 1μ" min. Plating Over Ni 50μ" min.
 - Soldertail: Plating Over G/F" min.
 - 2-2. Shell :
 - Solderability Ni 50μ" min. Over All
 - Contact And Tail Coplanarity To Be 0.10mm max.

GENERAL TOLERANCE		KINGCONN 皇海科技股份有限公司	
X.± 0.50	X.° ± 5°	名 (TITLE) MICRO SD 4.0 PUSH H:1.63MM SMD	
.X± 0.30	.X° ± 2°		
.XX± 0.20	.XX° ± 1°		
單位 (UNIT) mm	料號 (PART NO.) 7MSD4-F0-0003	圖號 (DWG NO.) 7MSD4-F0-0003	
審核 (APPROVAL)	核對 (CHECKED)	製圖 (DRAWN)	比例 (SCALE) 1:1
			張數 (SHEET) 2/2
			更改 (REV) A

